

ASSEMBLY NOTES:

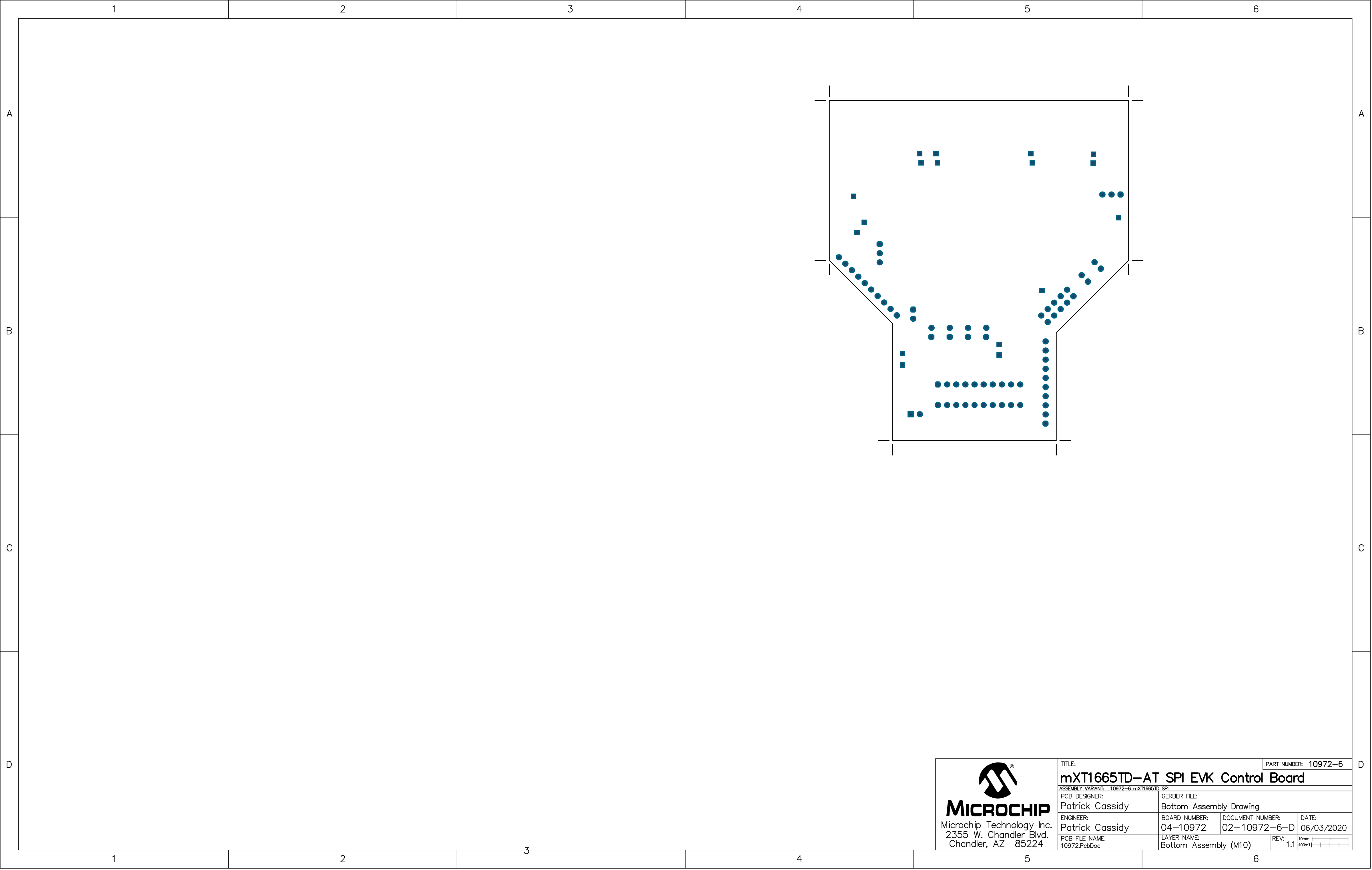
1. ALL COMPONENTS SHALL BE RoHS COMPLIANT.
2. ALL UNUSED THROUGH HOLE COMPONENT LOCATIONS SHALL BE FREE OF SOLDER.
3. ALL TEST POINT THROUGH HOLES (DENOTED TPxx) SHALL BE FREE OF SOLDER.
4. ALL COMPONENTS SHALL BE MOUNTED FLUSH TO THE BOARD, EXCEPT AS NOTED.
5. FINISHED BOARD SHALL BE FREE OF ALL RESIDUES.
6. ALL LEADS SHALL BE TRIMMED TO A MAXIMUM HEIGHT OF 2mm.
7. PLACE LABELS ON THE LOCATION INDICATED.

REV	ECO	Comments	Date
A0	N/A	First Issue	21st Jan 2015
B0	N/A	Inserted blanks in place of device ID	27th Aug 2015
B1	N/A	Changed to MCHP branding	11th July 2017
B2	N/A	Added RoHS, WEEE & CE symbols	8th Mar 2018
1	N/A	Q1, U3, U5 now MCHP parts Board number changed per Dev Tools ATM	7th Mar 2019



Microchip Technology Inc.  
2355 W. Chandler Blvd.  
Chandler, AZ 85224

TITLE:		PART NUMBER: 10972-6	
mXT1665TD-AT SPI EVK Control Board			
PCB DESIGNER:		GERBER FILE:	
Patrick Cassidy		Top Assembly Drawing	
ENGINEER:	BOARD NUMBER:	DOCUMENT NUMBER:	DATE:
Patrick Cassidy	04-10972	02-10972-6-D	06/03/2020
PCB FILE NAME:	LAYER NAME:	REV:	10mm 400m
10972.PcbDoc	Top Assembly (M11)	1.1	



TITLE:		PART NUMBER: 10972-6	
mXT1665TD-AT SPI EVK Control Board			
ASSEMBLY VARIANT: 10972-6 mXT1665TD SPI			
PCB DESIGNER:		GERBER FILE:	
Patrick Cassidy		Bottom Assembly Drawing	
ENGINEER:		BOARD NUMBER:	DOCUMENT NUMBER:
Patrick Cassidy		04-10972	02-10972-6-D
PCB FILE NAME:		LAYER NAME:	REV:
10972.PcbDoc		Bottom Assembly (M10)	1.1

10mm

400mil

